Silicon N Channel MOS FET High Speed Power Switching

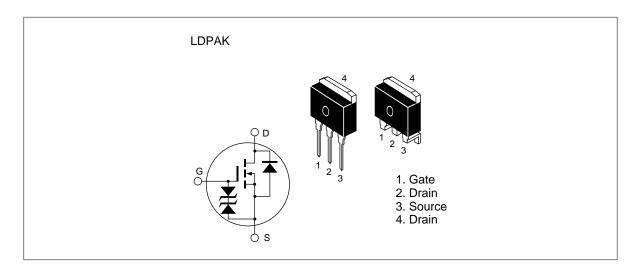
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ADE-208-760(Z) Target Specification, 1st. Edition Dec. 1, 1998

Features

- Low on-resistance $R_{DS} = 35 m\Omega \text{ typ.}$
- High speed switching
- 4V gate drive device can be driven from 5V source

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	150	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	30	A
Drain peak current	I Note1	120	A
Body-drain diode reverse drain current	I _{DR}	30	A
Avalanche current	Note3	30	A
Avalanche energy	E _{AR} Note3	67	mJ
Channel dissipation	Pch Note2	100	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %

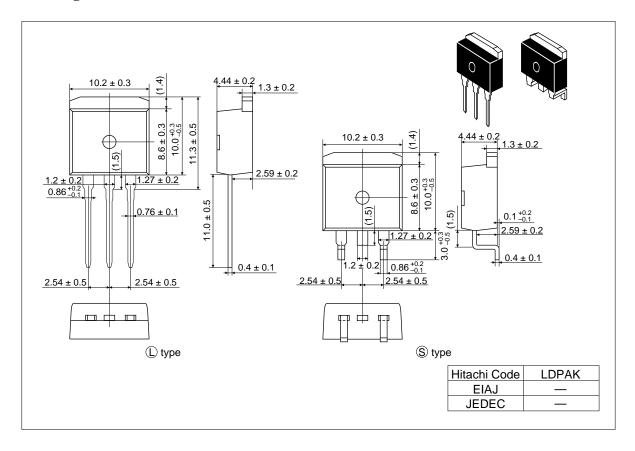
- 2. Value at $Tc = 25^{\circ}C$
- 3. Value at Tch = 25°C, Rg \geq 50 Ω

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	150	_	_	V	$I_{D} = 10 \text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 150 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.5	V	$I_D = 1 \text{mA}, V_{DS} = 10 \text{V}$
Static drain to source on state	R _{DS(on)}	_	35	45	mΩ	$I_D = 15A, V_{GS} = 10V^{Note4}$
resistance	R _{DS(on)}		42	75	mΩ	$I_D = 15A$, $V_{GS} = 4V^{Note4}$
Forward transfer admittance	y _{fs}	18	30	_	S	$I_D = 15A, V_{DS} = 10V^{Note4}$
Input capacitance	Ciss	_	2600	_	pF	V _{DS} = 10V
Output capacitance	Coss	_	820	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	350	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	25	_	ns	$I_D = 15A, V_{GS} = 10V$
Rise time	t _r	_	180	_	ns	$R_L = 2\Omega$
Turn-off delay time	t _{d(off)}	_	600	_	ns	_
Fall time	t _f	_	280	_	ns	_
Body-drain diode forward voltage	V _{DF}	_	0.95	_	V	$I_F = 30A, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	110	_	ns	$I_F = 30A, V_{GS} = 0$ diF/ dt =50A/ μ s

Note: 4. Pulse test

Package Dimensions (Unit: mm)



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